
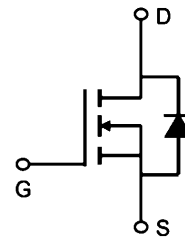
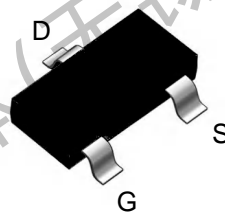
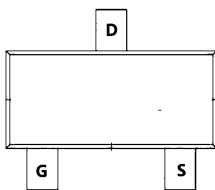


TM04N15MI

N-Channel Enhancement Mosfet

<p>General Description</p> <ul style="list-style-type: none"> • Low R_{DS(ON)} • RoHS and Halogen-Free Compliant <p>Applications</p> <ul style="list-style-type: none"> • Load switch • PWM 	<p>General Features</p> <p>V_{DS} =150V I_D =4.0A</p> <p>R_{DS(ON)} = 245 mΩ(Typ.)@ V_{GS}=10V</p> <p>100% UIS Tested 100% R_g Tested</p> 
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MI:SOT-23-3L



Marking: 04N15 OR 3N150

Absolute Maximum Ratings (T_C=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	150	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	4	A
I _D @T _A =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	2	A
I _{DM}	Pulsed Drain Current ²	15	A
P _D	Total Power Dissipation ³	3	W
EAS	Single Pulse Avalanche Energy ²	1.25	mJ
T _{STG}	Storage Temperature Range	-55 to 175	°C
T _J	Operating Junction Temperature Range	-55 to 175	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-ambient ¹	---	74	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	80	°C/W

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Electrical Characteristics (T_J = 25°C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	150	-	-	V
Gate-body Leakage current	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 150V, V _{GS} = 0V	T _J =25°C	-	1	μA
			T _J =100°C	-	100	
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	2.0	2.5	3.0	V
Drain-Source on-Resistance ⁴	R _{DS(on)}	V _{GS} = 10V, I _D = 4A	-	245	300	mΩ
Forward Transconductance ⁴	g _{fs}	V _{DS} = 10V, I _D = 4A	-	25	-	S
Dynamic Characteristics⁵						
Input Capacitance	C _{iss}	V _{DS} = 75V, V _{GS} = 0V, f = 1MHz	-	450	-	pF
Output Capacitance	C _{oss}		-	23	-	
Reverse Transfer Capacitance	C _{rss}		-	14	-	
Gate Resistance	R _g	f = 1MHz	-	1.5	-	Ω
Switching Characteristics⁵						
Total Gate Charge	Q _g	V _{GS} = 10V, V _{DS} = 75V, I _D = 1.5A	-	8.2	-	nC
Gate-Source Charge	Q _{gs}		-	1.5	-	
Gate-Drain Charge	Q _{gd}		-	2.2	-	
Turn-on Delay Time	t _{d(on)}	V _{GS} = 10V, V _{DD} = 75V, R _G = 6Ω, I _D = 1A, R _G = 75Ω	-	8.2	-	ns
Rise Time	t _r		-	10.2	-	
Turn-off Delay Time	t _{d(off)}		-	20.5	-	
Fall Time	t _f		-	15.3	-	
Drain-Source Body Diode Characteristics						
Diode Forward Voltage ⁴	V _{SD}	I _S = 1A, V _{GS} = 0V	-	-	1.2	V
Continuous Source Current	I _S	T _C = 25°C	-	-	4.0	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)} = 150°C.
2. The EAS data shows Max. rating . The test condition is V_{DD} = 25V, V_{GS} = 10V, L = 0.1mH, I_{AS} = 5A.
3. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
5. This value is guaranteed by design hence it is not included in the production test.

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Typical Characteristics

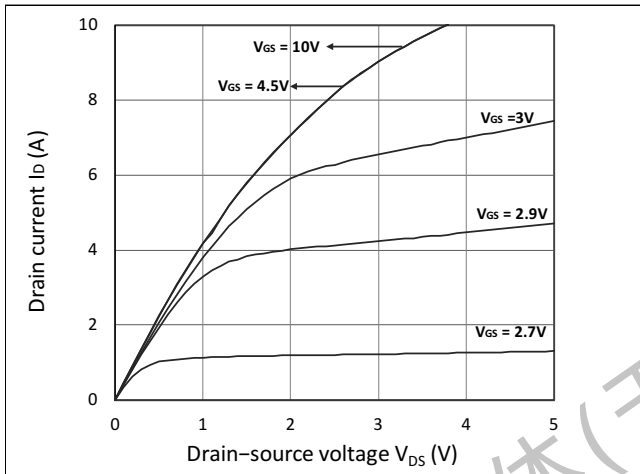


Figure 1. Output Characteristics

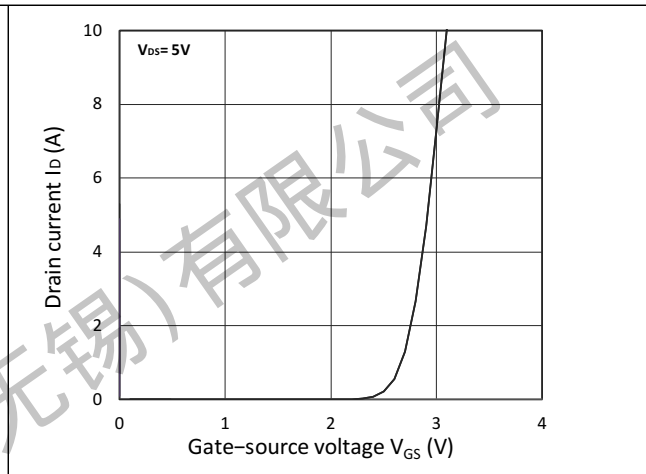


Figure 2. Transfer Characteristics

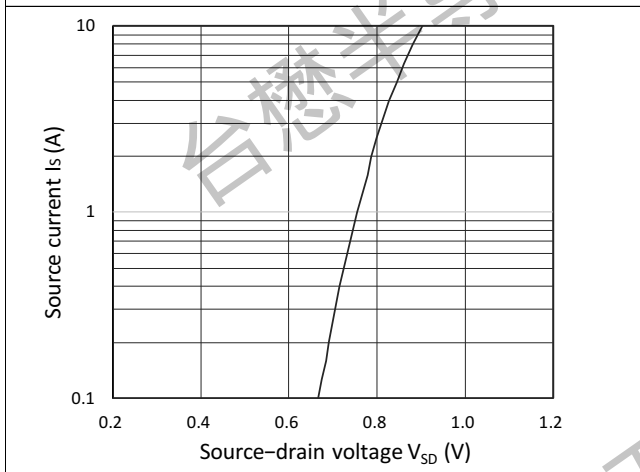


Figure 3. Forward Characteristics of Reverse

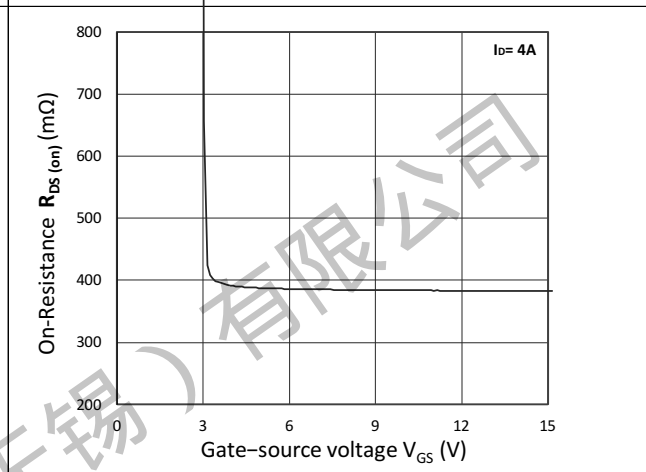


Figure 4. $R_{DS(on)}$ vs. V_{GS}

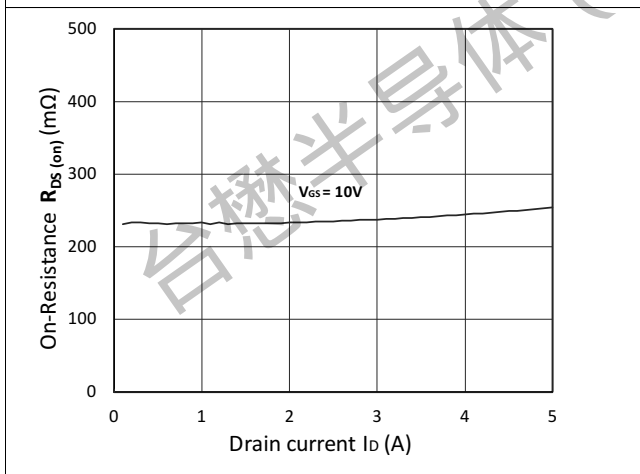


Figure 5. $R_{DS(on)}$ vs. I_D

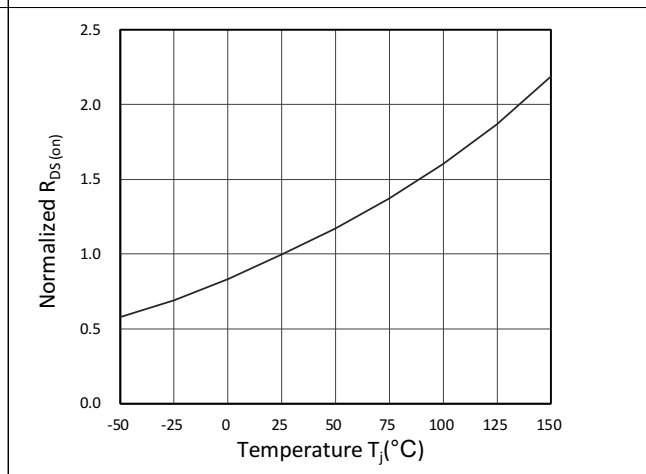


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

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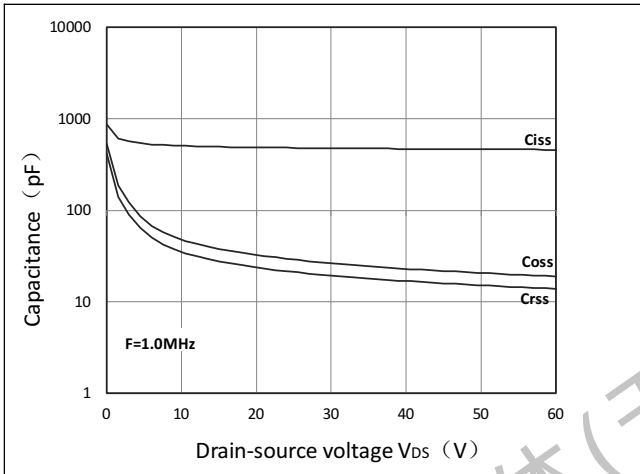


Figure 7. Capacitance Characteristics

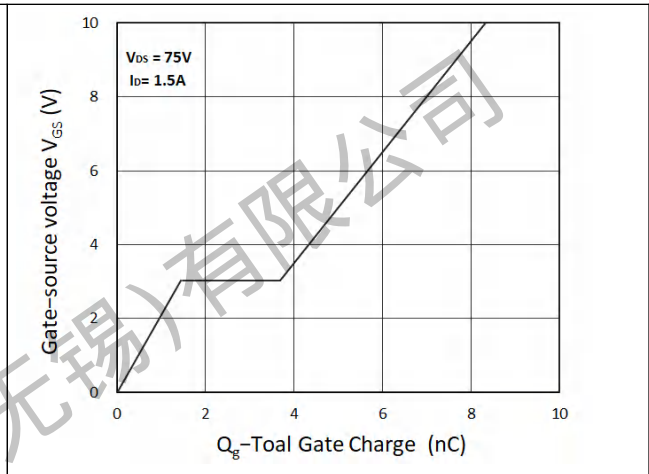


Figure 8. Gate Charge Characteristics

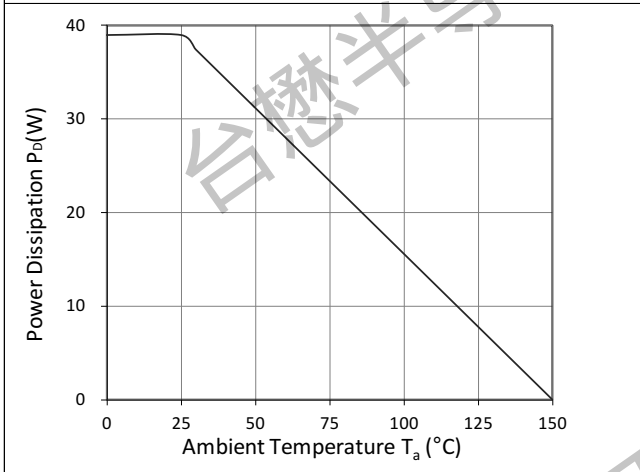


Figure 9. Power Dissipation

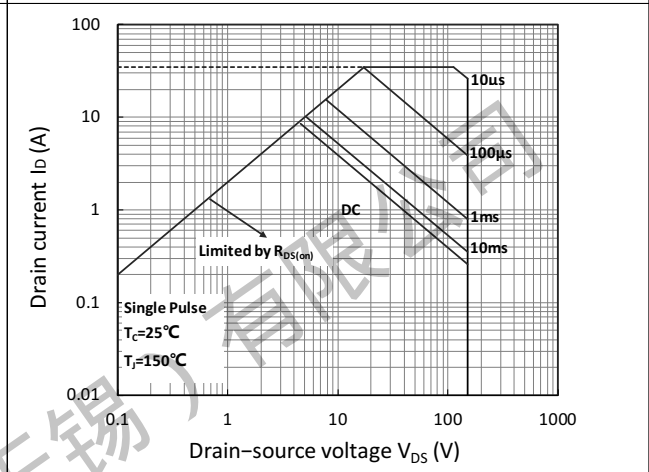


Figure 10. Safe Operating Area

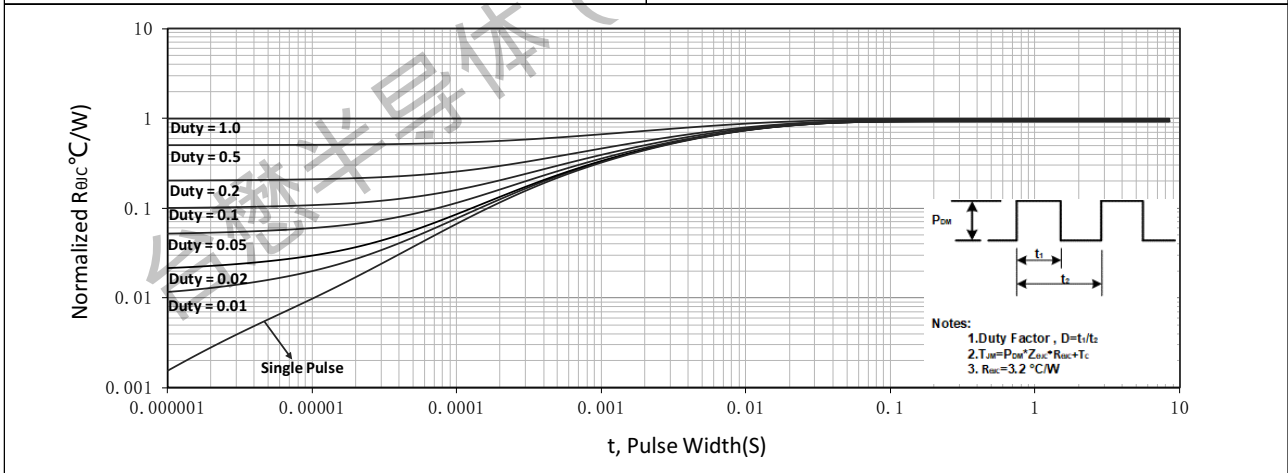
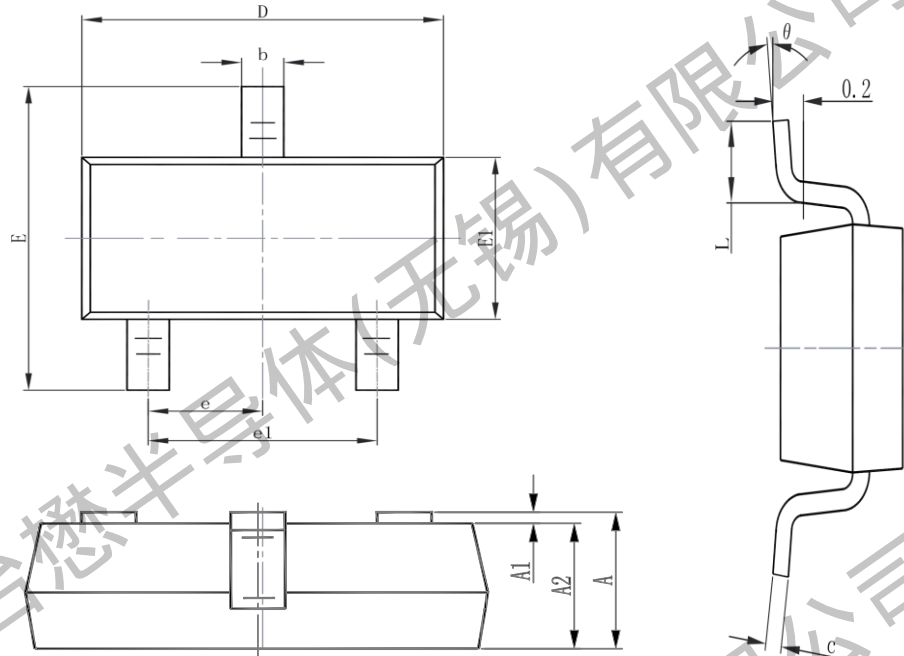


Figure 11. Normalized Maximum Transient Thermal Impedance

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N-Channel Enhancement Mosfet

Package Mechanical Data:SOT-23-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
theta	0°	8°	0°	8°

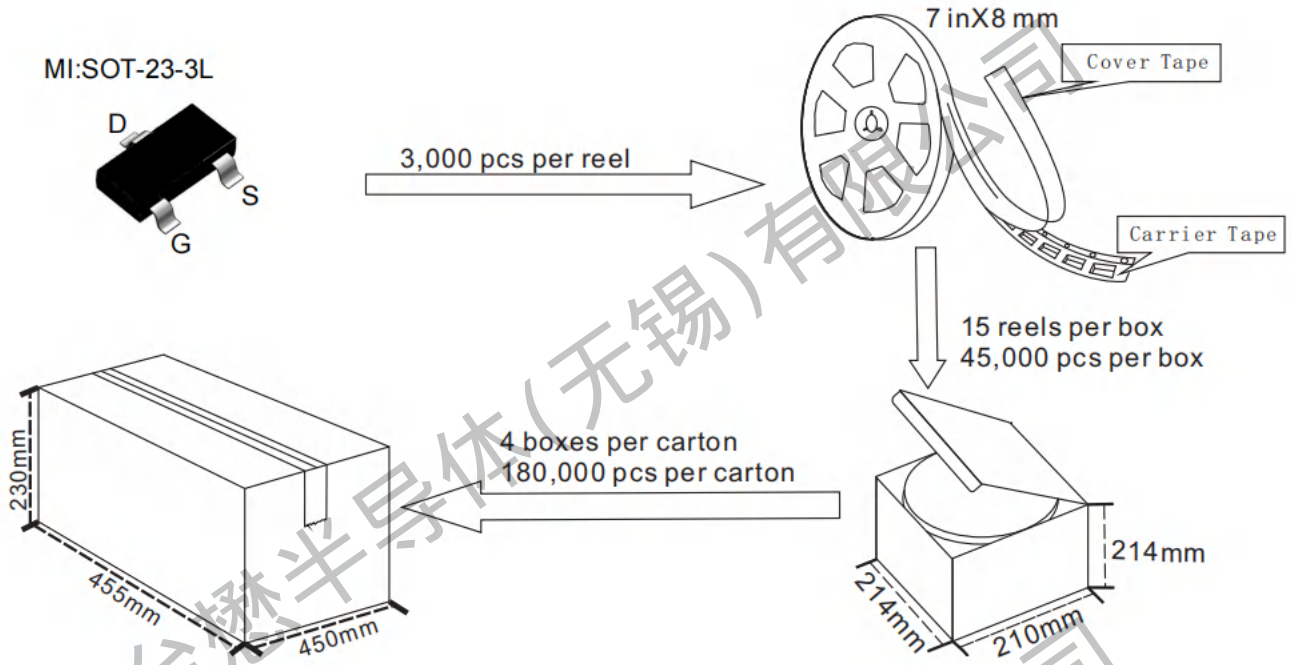


TM04N15MI

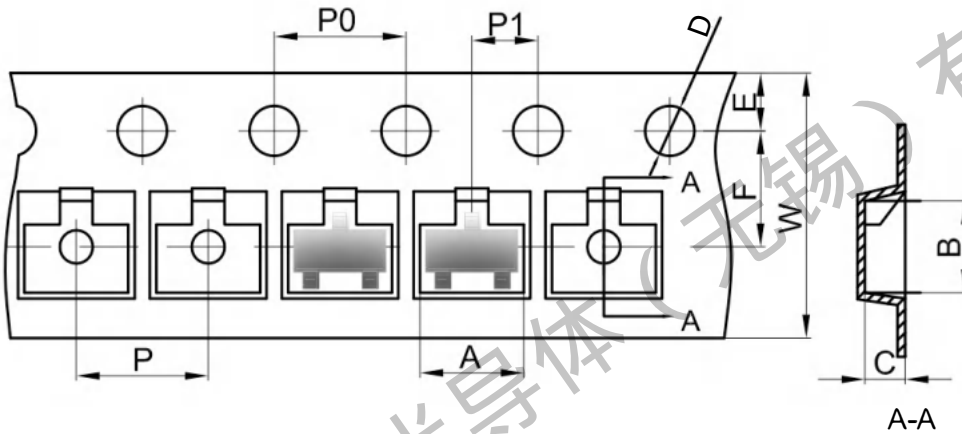
N-Channel Enhancement Mosfet

SOT-23-3L Packing

1.The method of packaging and dimension are shown as below figure. (Dimension in mm)



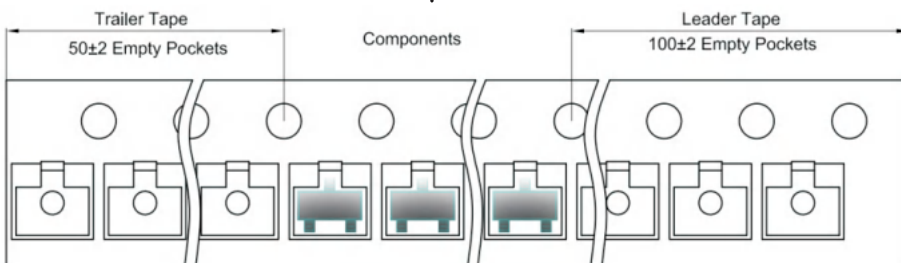
SOT-23-3L Embossed Carrier Tape



Dimensions are in millimeter

Pkg type	A	B	C	D	E	F	P0	P	P1	W
SOT-23-3L	3.40	3.0	1.22	Ø1.50	1.75	3.50	4.00	4.00	2.00	8.00

SOT-23-3LTape Leader and Trailer





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Revision history:

Date	Rev	Description	Page
2024.06.10	24.06	Original	